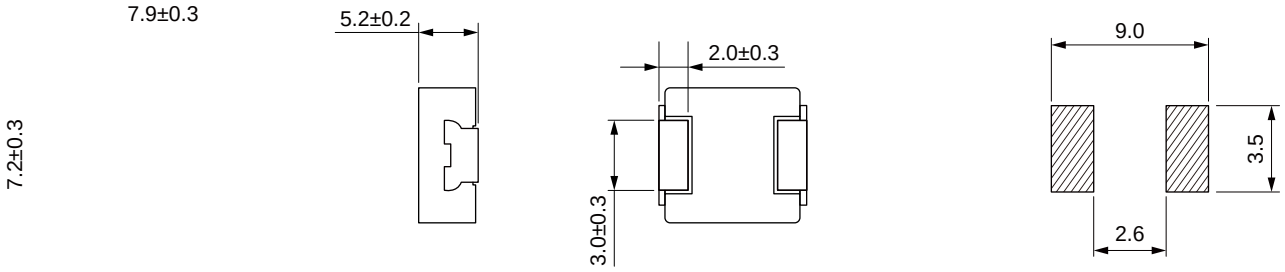
SMD Low Profile High Current Molded Inductor

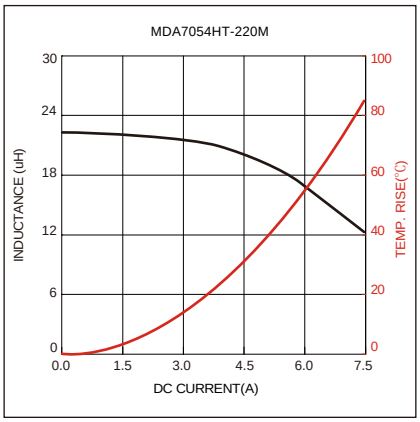
- Low loss realized with low DCR.
- ¦ fúNl· f2ø ōdzÎÎ y2λăŜΣ ŘdzŜ ú2 Ŏ2YLJ2ăλúŜ Ŏ2yãúNdzŎə2y´.
- 100% Lead(Pb)-Free and RoHS compliant.
- High performance (Isat) realized by metal dust core.
- !9/πvнллlljdzl·fλŮŜŘ.
- hLJŜNl·əyƎ ûŜYLJŜNl·údzNŜY πpp ú2 ьмpp c/ óλyŎfdzŘλyƎ ăŜfŦπúŜYLJŜNl·údzNŜ NλăŜú
- vdzl·yəűëY рллt/{

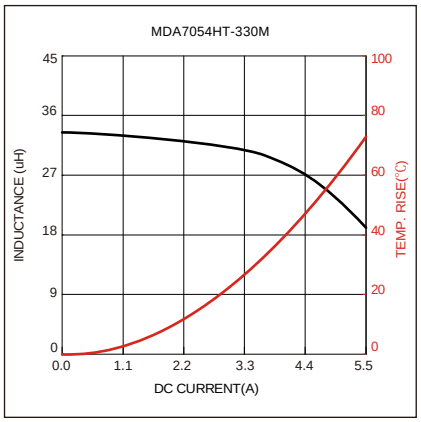
- lŜl·Řfl·YLJăΣ úl·λf fl·YLJă l·yŘ λyűŜNλ2N fλƎKəyƎ
- HVAC
- 522NăΣ øλyŘ2ø fλD l·yŘ ăŜl·ú Ŏ2yűN2f
- Audio subsystem
- Digrisẗm
-

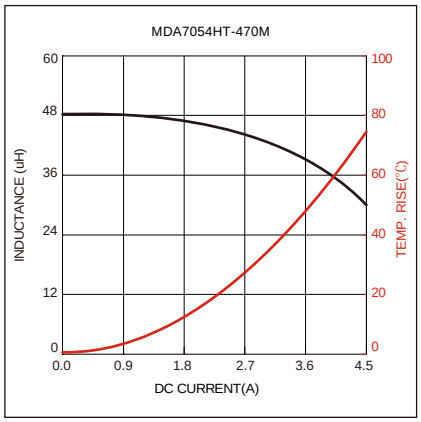


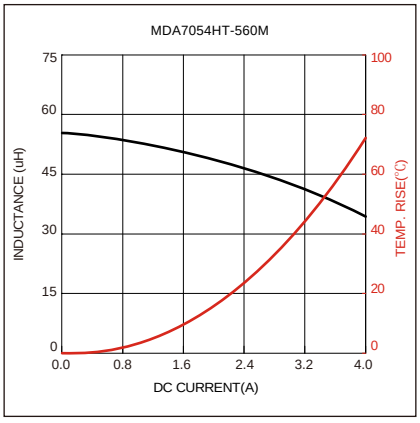
Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	Current Typ. (A)	Current Max. (A)	DC Resistance Typ.	DC Resistance Max.
MDA7054HT-1R5M	1.50	±20%	11.5	10.3	16.4	14.0	6.30	7.30
MDA7054HT-2R2M	2.20	±20%	9.80	8.70	15.0	12.7	9.90	11.4
MDA7054HT-3R3M	3.30	±20%	8.00	7.20	13.5	11.6	13.4	15.4
MDA7054HT-4R7M	4.70	±20%	7.00	6.30	13.2	11.2	18.2	20.9
MDA7054HT-5R6M	5.60	±20%	6.50	5.60	10.6	9.20	20.0	24.0
MDA7054HT-6R8M	6.80	±20%	6.20	5.50	10.2	8.70	23.1	26.6
MDA7054HT-8R2M	8.20	±20%	5.80	5.00	9.20	7.70	27.8	31.9
MDA7054HT-100M	10.0	±20%	5.20	4.70	8.10	6.90	33.0	38.0
MDA7054HT-150M	15.0	±20%	3.80	3.40	7.00	5.90	60.0	66.0
MDA7054HT-220M	22.0	±20%	3.30	3.00	6.30	5.40	85.0	93.5

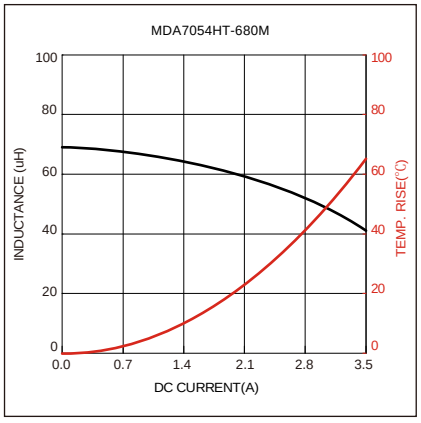
Typical Electrical Characteristics:

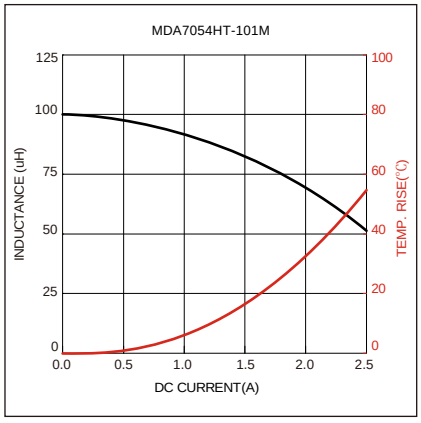

MDA7054HT-220M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
30
24
18
12
6
0
100
80
60
40
20
0
0.0
1.5
3.0
4.5
6.0
7.5


MDA7054HT-330M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
45
36
27
18
9
0
100
80
60
40
20
0
0.0
1.1
2.2
3.3
4.4
5.5

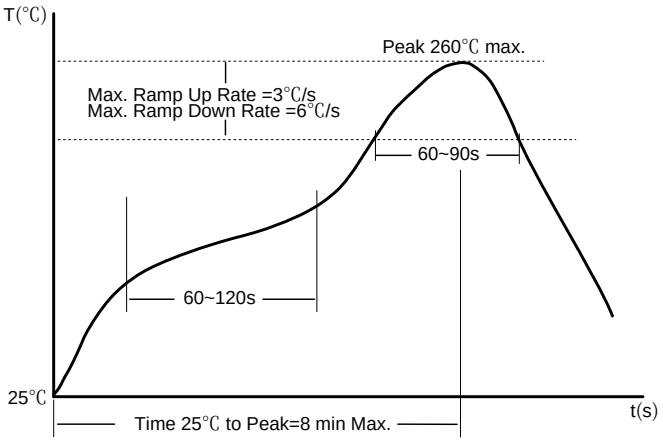

MDA7054HT-470M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
60
48
36
24
12
0
100
80
60
40
20
0
0.0
0.9
1.8
2.7
3.6
4.5


MDA7054HT-560M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
75
60
45
30
15
0
100
80
60
40
20
0
0.0
0.8
1.6
2.4
3.2
4.0


MDA7054HT-680M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
100
80
60
40
20
0
100
80
60
40
20
0
0.0
0.7
1.4
2.1
2.8
3.5


MDA7054HT-101M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
125
100
75
50
25
0
100
80
60
40
20
0
0.0
0.5
1.0
1.5
2.0
2.5

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

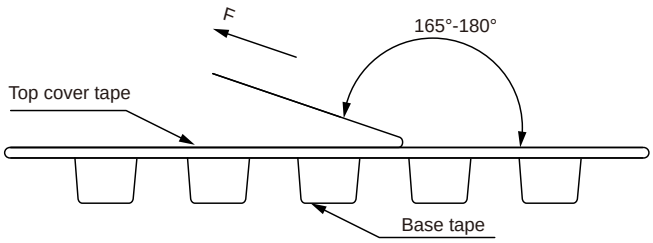
Max temperature: 260℃.

Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension：

Peel force of top cover tape:

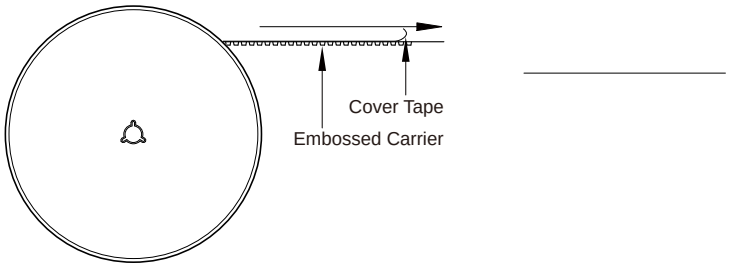


The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	K+Printing Inductance+period)

Reel Dimension：[mm]



Packaging Quantity: